

P-M8.4

Wire Bond Mold Package
For Dual Interface application (Controller)

Short Product Overview

May 2010

Chip Card & Security

P-M8.4 Short Product Overview	Ref.: Chip_Card_Product_Overview_11/09
Revision History: Current Version 05.10	
Previous Releases:	
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Important: Further information is confidential and on request. Please contact:
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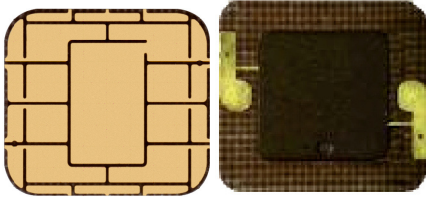
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Product name	P-M8.4
Picture	
Product description	Dual Interface Module 8 contacts CB 2 Antenna Contacts Epoxy Tape Wire Bond Mold
Typical Applications	Payment, Government Identification
Pitch	14.25 mm
Dimensions	13 x 11.8 mm
Thickness	max. 620µm
Contact Surface	NiAu
Delivery form	Tape on Reel Reel diameter 330mm
ISO - reference	ISO/IEC 7810 SO/IEC 7816-1 ISO/IEC 10373-1 / -3
Derivatives	

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